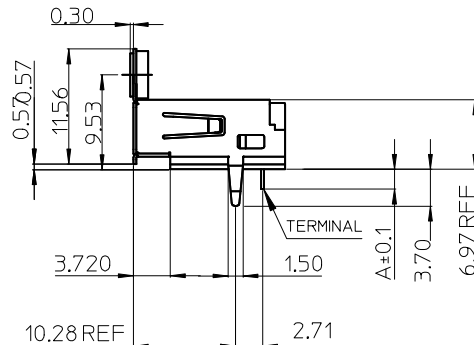
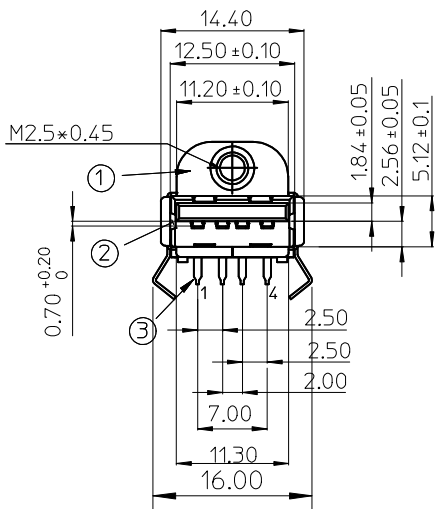


PCB LAYOUT (BOTTOM VIEW)



NOTES:

1. MATERIAL:

- ① METAL SHELL: COPPER ALLOY. SCREW: BRASS
- ② HOUSING: SEE CHART, 30% GLASS FIBER FILLES, UL94-V0.
- ③ TERMINAL: PHOSPHOR BRONZE

2. PLATING:

TERMINAL:

CONTACT AREA: (a) GOLD FLASH.

(b) GOLD (Au), THICKNESS=0.76 μM/30MNCH MINIMUM.

SOLDER TAIL: TIN PLATED, THICKNESS=1.875 μM/75MNCH MINIMUM.

UNDER PLATED: NICKEL (Ni), THICKNESS=1.25 μM/50MNCH MINIMUM.

METAL SHELL: SEE CHART.

3. RECOMMENDED PCB THICKNESS: SEE CHART

4. PRODUCT SPECIFICATION: FOR IR REFER TO PS-67643-002

FOR NON IR REFER TO PS-67643-003

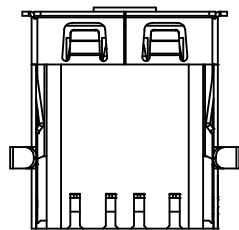
5. TORQUE FORCE SPEC: 2.50kg-cm Min, MEASURED AT BROKEN POINT.

6. TEST SUMMARY: FOR IR REFER TO TS-67643-002

FOR NON IR REFER TO TS-67643-003

7. PACKAGE: REFER TO PK-67643-002

8. LEAD FREE AND ROHS COMPLIANCE PRODUCT



REVISED EC NO: DRWN: FYANG05 CHKD: APPR:	DESCRIPTION 2013/05/09	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)	DIMENSION STYLE MM ONLY	SCALE 1:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
		▽=0		DRAWN BY IVY-LIN	DATE 2005/04/01	TITLE USB A TYPE RCPT SGL RA THRHOLE WITH UPPER FLG (LEAD-FREE VERSION)	Molex MOLEX INCORPORATED
		∇=0		CHECKED BY ALL IN	DATE 2005/04/01		
				APPROVED BY WWSCHANG	DATE 2005/04/01		
		MATERIAL NO.	DOCUMENT NO.				
			ANGULAR ± 3 °	SEE SHEET 2			
			DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	SIZE A4	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		SHEET NO. 1 OF 2

P/N	HOUSING MATERIAL	COLOR	CONTACT PLATING	METAL SHELL PLATING	REMARK
67643-0990	POLYESTER	BLACK	GOLD FLSAH	IR REFLOW PROCESS MATTE TIN PLATED AT SOLDER AREA THICKNESS=2.54 μM/100μMCH UNDER PLATE:NICKEL (Ni),(SOLDERING AVAILABLE)	NON IR
67643-1990	POLYESTER	WHITE			REFLOW PROCESS
67643-2990	HIGH TEMPERATURE NYLON	BLACK			FOR IR
67643-3990	HIGH TEMPERATURE NYLON	WHITE			REFLOW PROCESS
67643-0991	POLYESTER	BLACK	GOLD PLATING 0.76 μM/30μMCH	NON IR REFLOW PROCESS: MATTE TIN PLATED. THICKNESS=2.00 μM/80μMCH UNDER PLATE:NICKEL (Ni).	NON IR
67643-1991	POLYESTER	WHITE			REFLOW PROCESS
67643-2991	HIGH TEMPERATURE NYLON	BLACK			FOR IR
67643-3991	HIGH TEMPERATURE NYLON	WHITE			REFLOW PROCESS
PCB THICKNESS		1.60±0.05			
DIMENSION "A"		2.60			

P/N	HOUSING MATERIAL	COLOR	CONTACT PLATING	METAL SHELL PLATING	REMARK
67643-0980	HIGH TEMPERATURE NYLON	BLACK	GOLD FLSAH	IR REFLOW PROCESS MATTE TIN PLATED AT SOLDER AREA THICKNESS=2.54 μM/100μMCH UNDER PLATE:NICKEL (Ni),(SOLDERING AVAILABLE)	FOR IR
67643-1980	HIGH TEMPERATURE NYLON	WHITE			
67643-0981	HIGH TEMPERATURE NYLON	BLACK	GOLD PLATING 0.76 μM/30μMCH		
67643-1981	HIGH TEMPERATURE NYLON	WHITE			
PCB THICKNESS		1.20±0.05			
DIMENSION "A"		2.00			

REVISED ECT NO: DRWN:FYANG05 CHKD: APPR:	2013/05/09 DESCRIPTION REV	QUALITY SYMBOLS ▽=0 ◻=0	GENERAL TOLERANCES (UNLESS SPECIFIED) mm INCH 4 PLACES ± --- ± --- 3 PLACES ± --- ± --- 2 PLACES ± 0.25 ± --- 1 PLACE ± 0.25 ± --- ANGULAR ± 3 °	DIMENSION STYLE MM ONLY DRAWN BY DATE IVY-LIN 2005/04/01 CHECKED BY DATE ALL IN 2005/04/01 APPROVED BY DATE WWSCHANG 2005/04/01	SCALE 1:1 TITLE USB A TYPE RCPT SGL RA THRHOLE WITH UPPER FLG (LEAD-FREE VERSION)	DESIGN UNITS METRIC THIRD ANGLE PROJECTION		
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS			MATERIAL NO. SEE TABLE	MOLEX INCORPORATED DOCUMENT NO. SD-67643-004	SHEET NO. 2 OF 2	
					SIZE A4	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		